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SCBS873A-FEBRUARY 2008-REVISED APRIL 2008

S1

GTL\_REF

DCK PACKAGE

(TOP VIEW)

6

5

4

1

2

3

GND

S0 🗌

## SELECTABLE GTL VOLTAGE REFERENCE

#### FEATURES

- V<sub>DD</sub> Range: 3.0 V to 3.6 V
- V<sub>TT</sub> Range: 1 V to 1.3 V
- Provides Selectable GTL V<sub>REF</sub>
  - $0.615 \times V_{TT}$
  - $-~0.63\times V_{TT}$
  - $0.65 \times V_{TT}$
  - $0.67 \times V_{TT}$
- ±1% Resistor Ratio Tolerance
- Ambient Temperature Range: –40°C to 85°C
- ESD Protection Exceeds the Following Levels Tests (Tested Per JESD-22):
  - 2500-V Human-Body Model (A114-B, Class II)
  - 250-V Machine Model (A115-A)
  - 1500-V Charged-Device Model (C101)

### **DESCRIPTION/ORDERING INFORMATION**

The SN74GTL3004 provides for a selectable GTL Voltage Reference (GTL  $V_{REF}$ ). The value of the GTL  $V_{REF}$  can be adjusted using S0 and S1 select pins.

The S0 and S1 pins contain glitch-suppression circuitry for excellent noise immunity. When left floating, the S0 and S1 control input pins have 100-k $\Omega$  pullups that set the GTL V<sub>REF</sub> default value to the 0.67 × V<sub>TT</sub> ratio (S0 = 1 and S1 =1).

#### **ORDERING INFORMATION**

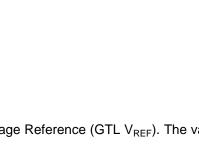
T <sub>A</sub>	PACKAGE <sup>(1)</sup>	(2)	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
–40°C to 85°C	SOT (SC70) – DCK	Tape and reel	SN74GTL3004DCKR	2TK	

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

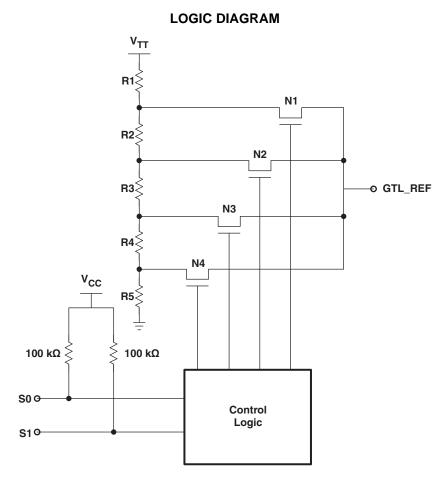


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#### **FUNCTION TABLE**

S1	S0	RATIO SET
0	0	$0.615  imes V_{TT}$
0	1	$0.63  imes V_{TT}$
1	0	$0.65  imes V_{TT}$
1	1	$0.67  imes V_{TT}$

2



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#### **ABSOLUTE MINIMUM AND MAXIMUM RATINGS**<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT
V <sub>DD</sub>	Power supply voltage range	-0.3	4.6	V		
V <sub>TT</sub>	Termination voltage range <sup>(2)</sup>	Termination voltage range <sup>(2)</sup>				
V <sub>IN</sub>	Control input voltage range (2)				V <sub>DD</sub> + 0.3	V
$V_{GTL\_REF}$	Resistor output voltage range <sup>(2)</sup>				$V_{DD}$ + 0.3	V
I <sub>IK</sub>	Input clamp current	V <sub>IN</sub> < 0			-18	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0			-18	mA
	Continuous current through V <sub>DD</sub> or GND			100	mA	
$\theta_{JA}$	Package thermal impedance <sup>(3)</sup>	DCK package			259	°C/W
T <sub>stg</sub>	Storage temperature range			-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

(3) The package thermal impedance is calculated in accordance with JESD 51-7.

### **RECOMMENDED OPERATING CONDITIONS**<sup>(1)</sup>

	PARAMETER	MIN	TYP	MAX	UNIT
$V_{DD}$	Power supply voltage	3	3.3	3.6	V
V <sub>TT</sub>	Termination voltage	1	1.1	1.3	V
$V_{\text{IH}}$	High-level control input voltage	$V_{DD}  imes 0.65$			V
VIL	Low-level control input voltage			$V_{\text{DD}} \times 0.35$	V
VI	Control input voltage	0		V <sub>DD</sub>	V
I <sub>OUT</sub>	I <sub>GTL_REF</sub> , GTL_REF output current		0	10	μA
PW	Control input pulse width	110			ns
T <sub>A</sub>	Operating free-air temperature	-40		85	°C

 All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow of Floating CMOS Inputs, literature number SCBA004.

### **ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range,  $T_A = -40^{\circ}C$  to  $85^{\circ}C$ ,  $V_{DD} = 3.3 \text{ V} \pm 10\%$ , GND = 0 V (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VIK	Control	$V_{DD} = 3.6 \text{ V}, \text{ I}_{IN} = -18 \text{ mA}$			-1.8	V
I <sub>IN</sub>	Control	$V_{DD} = 3.6 \text{ V}, \text{ V}_{IN} = \text{GND}$			43	μA
I <sub>DD</sub>		$V_{DD} = 3.6 \text{ V}, \text{ V}_{IN} = \text{GND}, \text{ I}_{O} = 0 \text{ mA}$			85	μA
R	End-to-end resistance	$V_{DD} = 3.6 \text{ V}, \text{ V}_{TT} = 1.1 \text{ V}, \text{ I}_{O} = 0 \text{ mA}$	4.25	7.12	10.6	kΩ
	(CTL) (	$I_{O} = 0 \ \mu A$ , See Figure 1	-1		1	%
	GTL V <sub>REF</sub> accuracy <sup>(1)</sup>	$I_O = 10 \ \mu$ A, See Figure 1	-7		7	70

 GTL V<sub>REF</sub> accuracy is used to compare measured GTL\_VREF voltage versus expected GTL\_VREF voltage as determined by control inputs S0 and S1. The resistor ratio tolerance is incorporated into this parameter.

#### SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range,,  $T_A = -40^{\circ}C$  to  $85^{\circ}C$ ,  $V_{DD} = 3.3 \text{ V} \pm 10\%$ , GND = 0 V (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
PSR	Power supply rejection			-58		dB
	Pulse rejection				40	ns

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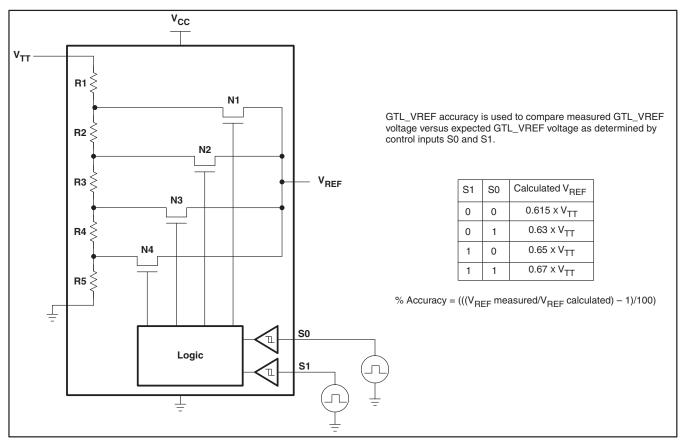


Figure 1. GTL\_REF Accuracy

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#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins P	ackage Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74GTL3004DCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74GTL3004DCKRG4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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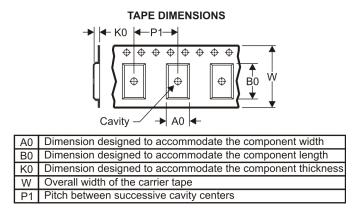
# PACKAGE MATERIALS INFORMATION

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#### TAPE AND REEL INFORMATION





### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	· ·	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74GTL3004DCKR	SC70	DCK	6	3000	180.0	9.2	2.3	2.55	1.2	4.0	8.0	Q3

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18-Jun-2011



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74GTL3004DCKR	SC70	DCK	6	3000	205.0	200.0	33.0

DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-203 variation AB.



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